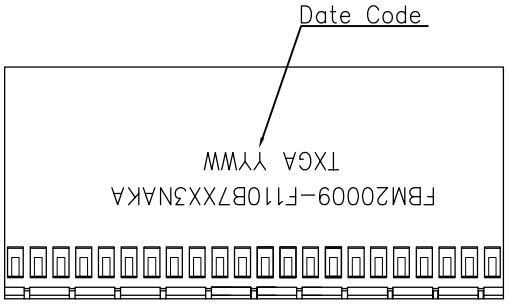
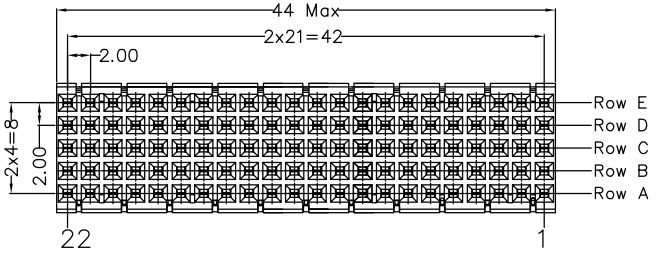
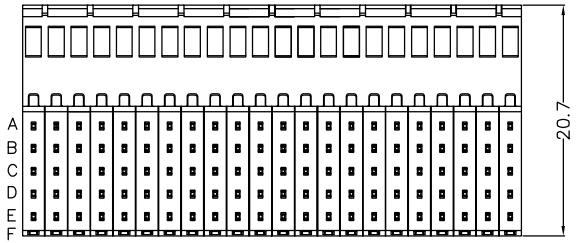
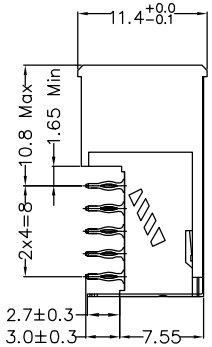
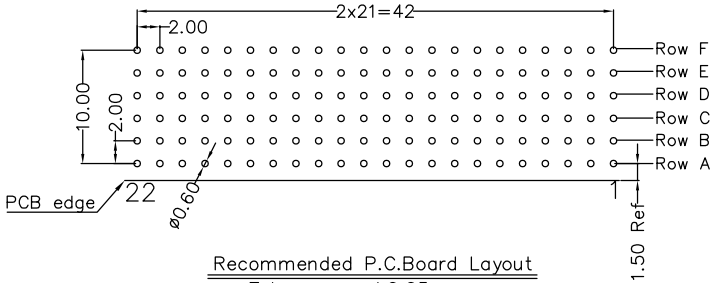
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD











Recommended P.C.Board Layout
Tolerances: ±0.05

SPECIFICATIONS

Electrical Performances
- Current Rating: 1.0A AC(rms)/DC
- Voltage Rating: 500V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 10000 MΩ MIN
- Withstanding Voltage: 750V AC r.m.s

Material and Plating
- Housing: LCP (UL 94V-0)
- Rear Bracket: PBT (UL 94V-0)
- Contact: Copper alloy/Gold plated on contact area and matte tin plated on tails,nickel under plated over all

Environmental Characteristics
- Temperature Range-Operating: -55℃~+125℃
- Storage temperature : -40℃~+70℃

Ordering Information

FBM	200	09	—	F	110	B	7	XX	3	NA	K	A
1	2	3		4	5	6	7	8	9	10	11	12

1	Category	2	Series Number	3	Distinction No.	4	Gender	5	Circuits	6	Entry Angle		
	FBM-HM Back plane connector		200-Pitch2.0mm		09		F-Female		110		B-90° Angle		

7	Plating	8	Thickness of Plating	9	Material-Resin	10	Color-Resin	11	Packaging	12	TYPE
	7-Selective gold plated on contact area and matte tin plated on tails		00-Gold flash 01-0.025μm 03-0.075μm Custom plate available		3-LCP		NA-Natural		K-Tray		A-A Type

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	TXGA Building Technology Cornerstone
			LEO	21/SEP/22	FBM20009-F110B7XX3NAKA	FBM20009	
DESIGN UNITS METRIC(mm)	GB 1804-m	X.' ±5'	CHECKED BY	DATE	TITLE		
	30~120 ±0.30	X.X' ±2'	GISELLE	21/SEP/22	HM Back plane connector Pitch 2.0mm Female(Press fit)	REV 0	SHEET NO. 1/1
SCALE 1.5:1	6~30 ±0.20	X.XX' ±1'	DRAWN BY	DATE			
SIZE A4	0~6 ±0.10	X.XXX' ±0.5'	HJP	21/SEP/22			

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